SOLDERING APPARATUS AND A METHOD THEREOF

ABSTRACT

A soldering method and apparatus in which a printed board, that cream solders are applied on lands at the position where leads of electronic parts are to be soldered and the leads of the electronic parts are provided to the lands, is fed to the soldering position, the cream solders of the fed printed board are spot heated and melted to solder the leads of the electronic parts to the lands, the molten solders are solidified by forced cooling to fix the leads of the electronic parts to the lands, and the printed board on which the leads of said electronic parts are fixed to the lands with the solidified solders, is discharged from said soldering position.

Figure 1